

**ABSTRACT OF THE DISCLOSURE**

The present invention provides an economical package for housing semiconductor chip that allows a semiconductor chip to operate normally and stably over long periods by efficiently transferring heat generated during the operation of the semiconductor chip to the package mount substrate.

A package for housing semiconductor chip that has a substrate, whose upper face is provided with a mounting space whereon a semiconductor chip is mounted, and whose opposite sides are provided with a screw mounting part which is a through-hole or notch; a frame, which is provided on the upper face of the substrate so as to enclose the mounting space and whose side or top has a joint for an input/output terminal; and an input/output terminal, which is connected to the joint, wherein at least a portion of the substrate below the semiconductor chip mounting space thereof comprises a metal-diamond composite that is produced by infiltrating a base material in which diamond grains are joined via a metal carbide with a metal containing copper and/or silver as the main component, and the other part including the screw mounting part consists of metal.